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Corrosion Resistance Enhancement of AZ91 Magnesium Alloy Using Ni-P Interlayer and Electrophoretic Deposited 3YSZ Coating

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 ARSSTRACT
 ARENT ARCONS
 ARENT *he zirconia stabilized by 3mol % Y2O³ (3YSZ) was applied onto the surface of the magnesium alloy AZ91D using electrophoretic deposition (EPD) from a non- aqueous solution. A Ni-P interlayer between the substrate and YSZ coating was also prepared by electroless plating. Finally, coatings were heat treated in control atmosphere at 400 °C. The preparation, microstructure and corrosion resistance of the coatings were investigated. Scanning electron microscope (SEM) was used to investigate the morphology of coatings. In addition, compositions of surface were determined by X-ray diffraction (XRD). The corrosion resistance of the coatings was evaluated by electrochemical impedance spectroscopy (EIS) in 3.5% NaCl solution. Also, the stability of coating was investigated by the Rockwell C indentation test (VDI 3198 norm). The results indicate that Ni-P interlayer can improve the quality of zirconia coating on the surface. Also, the Ni-P interlayer and YSZ coating increase the charge-transfer resistance of AZ91D surface in chloride solution. Prog. Color Colorants Coat. 9 (2016), 151-162 © Institute for Color Science and Technology.* T

1. Introduction

Magnesium and its alloys are the lightest structural metals which their density are about one-fourth of that of steel and two-thirds of that of aluminum. Therefore, they are attractive in automotive, aerospace, power tools and 3C (computer, communication and consumer products) industries. However, magnesium and its alloys are not corrosion resistance under various aqueous or humid conditions. So, the relatively low corrosion resistance of magnesium alloys limits their

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applications in industries [1].

The simplest way to protect the surface of Magnesium alloys is coating. The coatings can protect the surface by creating a barrier between the surface of alloy and its environment [2]. There are different processes for coating of magnesium and its alloys which each has their own advantages and disadvantages [2]. Organic and inorganic coatings can be applied onto magnesium alloys. Organic coatings

usually have poor adhesion if they are applied without an appropriate pre-treatment [3]. Furthermore, inorganic coatings can also be applied onto the surface of the magnesium alloys to improve their corrosion resistance, however, similar to organic coatings, they have poor adhesion to magnesium substrate [4]. The previous studies show that the zirconia coating onto the magnesium alloys can significantly improve the corrosion resistance of these alloys [5, 6].

The ceramic coatings can be applied by the electrophoretic deposition (EPD) that is a simplest and fastest method for coating of inorganic powders from colloidal suspensions [7]. The EPD process includes two steps. First, the charged particles which are suspended in liquid migrate toward an electrode under the effect of electrical field and in the second step, the particles that deposit on the surface of electrode produce a dense, compact and usually thick film [8, 9].

First, the charged particles which are

incouting [14]. Electroless plated Ni

liquid migrate toward an electrode under

lectrical field and in the second step, the K⁻¹ which is close to the thermal expansion coefficien Two groups of parameters affect the characteristics of EPD process: those which are related to the suspension and those related to the physical parameters such as potential, deposition time, the nature of electrodes, etc. During deposition of charged particles onto a substrate by EPD, part of electric current carried not only by the charged particles but also by free ions co-existing in the suspension. In addition, it is believed that the accumulation of ions at the electrodes during the electrophoretic deposition can decrease the deposition rate. On the other hand, the conductivity of the suspension in EPD process is a key factor. Thus, it has been pointed out that if the conductivity of suspension is high, the particle motion will be slow. Therefore, the solubility of the substrate in the suspension can affect the stability and deposition rate of the particles [10]. Also, a heat treatment or high temperature sintering is usually required in order to further densify the deposits and reduce their porosity [9].

The high temperature sintering is a main disadvantage in EPD of ceramic coatings on metal substrate, because the high temperature can damage metal substrate [11]. Another problem is the difference between the expansion coefficients of magnesium

alloys and ceramic coatings (about 15×10^{-6} K⁻¹ at 20 °C) [12, 13]. Therefore, during thermal treatment, the change of volume of metal substrate can produce stresses which can lead to cracking or even delamination of coating [13].

Some studies show that some metal powders such as Al, Ni can be added to the EPD suspension to increase the density of the ceramic coatings at lower sintering temperatures [11, 14]. Also, the Ni electroless interlayer can improve the adherence and density of the YSZ coating on metal substrate. During the heat treatment, the volume expansion associated with oxidation of Ni can partially increase the density of coating [14]. Electroless plated Ni-P layer has a thermal expansion coefficient of 12×10^{-6} K⁻¹ $\sim 14 \times 10^{-6}$ $K⁻¹$ which is close to the thermal expansion coefficient value of magnesium alloy substrate [12].

In other words, Ni–P electroless coating can be a suitable candidate as interlayer between top coat (3YSZ) and magnesium alloy substrate. The Electroless Nickel (EN) plating is a widely used surface modification technology due to superior hardness and corrosion resistance of the deposit [15]. The EN coatings on the magnesium alloys exhibit a nodular morphology with good adherence to substrate [16].

The aim of this study is to apply the YSZ coating on AZ91D alloy by EPD process and investigate the effect of Ni-P interlayer on the compactness of the YSZ coating on AZ91D substrate. Finally, the corrosion resistance of coated alloy was studied.

2. Experimental method

The composition of AZ91D magnesium alloy which was used as the substrate is listed in Table 1. Samples of AZ91D were cut into the size of 12 mm \times 12 mm \times 2 mm. Before conducting the coating process, the specimens were progressively abraded using emery papers of grade number 80 to 800, then degreased in acetone. Finally, alkaline cleaning was carried out to remove soils and greases.

Table 1: Chemical composition of AZ91D used in this study.

			Mg Al Zn Mn Cu Ni Fe	
			Bal. 8.3 0.35 0.12 0.03 0.002 0.005	

In the next step, the electroless plating of Ni-P interlayer was finished by alkaline cleaning, acid pickling, activation, and electroless plating. The solution composition and operation conditions of electroless plating of Ni-P interlayer is listed in Table 2. Also, the samples were heat treated at 400 ± 10 °C for 60 min in atmosphere-controlled furnace.

Solution with 1:1 volume ratio and then the solution with the other celectrice (S.C.B.)

Also, I₃ (0.1 g/L) was added to the perform these tests, a sinusoidal potent

an additive for charging the particles in mV amplitu Finally, to produce a dense and homogeneous green film of 3YSZ particles on the magnesium alloy with the Ni-P interlayer, the 3YSZ powders (10 g/L) with mean particle size of 50 nm were dispersed in ethanolacetyl acetone solution with 1:1 volume ratio and then were stirred. Also, I_2 (0.1 g/L) was added to the suspension as an additive for charging the particles in the suspension and the slurry was ultrasonically vibrated for 10 min. Again, the magnesium alloy with the Ni-P interlayer was selected as the cathode and the stainless steel 316L as the anode in the cell of EPD. The distance of the electrodes was fixed at 1 cm during deposition. An applied voltage of 40 V was used for the deposition of 3YSZ particles in a period of 3 min. The coated samples were heat treated at 400 ± 10 °C in air for 60 min. The test solutions were prepared using analytical grade chemicals (Merck Co.). In addition, the samples were coded based on preparation and coating method that is identified in Table 3.

The surface morphology of the coatings was observed by SEM (Tescan MIRA3 FEG-SEM, Czech

Republic). The phase analysis of the samples was determined by X-ray diffraction (EQuniox 3000, France). Furthermore, potentiostatic impedance tests were done in 3.5 wt% NaCl solution at open circuit potential using a potentiostat/galvanostat (EG&G, PARSTAT 2263, USA) equipped with electrochemical impedance spectroscopy (EIS) module.

A 3-electrode setup was used for the EIS tests. In this setup, AZ and YNi-AZ samples were used as the working electrode. The auxiliary electrode and the reference electrode in the cell were 316L stainless steel and saturated calomel electrode (SCE), respectively. To perform these tests, a sinusoidal potential wave with 10 mV amplitude in the frequency range between 100 KHz and 0.01 Hz was applied to the samples.

The coating adhesion to AZ91D substrate was evaluated using Rockwell C indentation which is standard technique commonly used to quantify the interfacial strength of coating-substrate systems. During the Rockwell C indentation test, a cone-shaped diamond 120° tip (200 μm in radius) was indented perpendicularly onto the coating applying a normal 150N. The results of the test were qualitatively evaluated by comparing the SEM images of the crack network [17]. Therefore, the feature with only a few minor cracks after indentation indicates a good bonding while the other features with extensive delamination of the coating indicate very poor adhesion to substrate.

Procedure	Bath Compositions (Per liter)	Condition			
Acid pickling	$CrO_3 = 125$ g $HNO3(70%)=110$ mL	Room temperature, stirring for 60 s			
Activation	$HF(40\%) = 358$ mL	Room temperature, stiring for 10 min			
	$NiSO_4.6H_2O=20$				
	HF $(40\%)=12$ ml				
	$C_6H_8O_7 \cdot H_2O=5$ g	75° C.			
Ni plating	$NH4F=10 g$	$pH = 6.2$			
	$NaH_2PO_2 \cdot H_2O=20g$	stirring for 2 h			
	$NH3·H2O$ (25%)=30 ml				
	Thiourea= 1×10^{-3} g				

Table 2: Electroless plating procedure of Ni–P on the Mg alloy substrate.

Table 3: Code of samples based on preparation and coating process.

3. Results and discussion

3.1. Ni-P interlayer

as deposited on AZ91D alloy from a bath depends on the bath and plating con

Ari-P layer is composed of fine nodules at complex agents [20]. In other words, the infinite

wi-P layer is composed of fine nodules

uniflower" Ni-P layer was deposited on AZ91D alloy from a bath with pH=6.2 and then was heat treated in the furnace at 400°C. The Ni–P layer is composed of fine nodules that have "cauliflower" shape (Figure 1 (a)). Micropores are distributed on the surface of these nodules (Figure 1(b)). Analyzed EDS (Figure 1(c)) of the nodules showed that the compositions of the layer were identified as 0.79 wt.% phosphorus and 75.14 wt.% nickel.

The percentage of P in Ni-P interlayer is related to pH of the bath, so that by increasing the pH, the nickel reduction reaction is accelerated according to equation (1), on the contrary, the phosphorous reduction is retarded according to equation (2). Therefore, in the acidic baths, the percentage of P is more than in basic ones [18].

$$
Ni^{2+} + H_2PO_2^- + H_2O \rightarrow Ni + HPO_3^{2-} + 3H^+ \tag{1}
$$

$$
H_2PO_2^- + \frac{1}{2}H_2 \to H_2O + OH^- + P \tag{2}
$$

1.7 % of magnesium is also detected in the coating that is due to the dissolution of magnesium surface during the fluoride activation and further co-deposition with the Ni during the electroless plating.

Also, as it is seen from Figure 1, some pores are observed between the nodules. They can be related to the H_2 releasing that accompanies with the deposition of Ni-P according to equation (3). Therefore, H_2 produces some micro-pores on the Ni-P surface.

$$
2H^+ + 2e^- \rightarrow H_2 \tag{3}
$$

The cross section of the Ni-P coating is shown in

Figure 2. According to Figure 2, the thickness of the coating is about 32 µm. The coating thickness is usually a function of deposition rate which in turn depends on the bath and plating conditions [19] and complex agents [20]. In other words, the high thickness of Ni-P layer can be related to the time of deposition that is 120 min. On the other hand, by increasing the time of deposition, the probability of formation of pores and porosity increases, however, the Ni-P layer can bond well to substrate because of the existence of a stronger metal-to-metal bonding during the EN deposition [18].

3.2. 3YSZ coating

In order to coat the YSZ particles on AZ91D alloy coated with Ni-P interlayer, the YSZ particles were dispersed in the ethanol-acetyl acetone solution. The YSZ particles charged via adsorption of protons which are formed by the reaction between acetyl acetone/ethanol and iodine. The addition of iodine to ketone solvents can lead to the production of proton and iodide ions as represented by equations (4) and (5) [21]:

$$
CH3-CO-CH2-CO-CH3+2I2\rightarrow
$$

ICH₂CO-CH₂-CO-CH₂I+2I⁺+2H⁺ (4)

$$
CH3-CH2-OH+I2\rightarrow
$$

ICH₂-CH₂-OH+H⁺+I⁻ (5)

Therefore, the protons generated will be adsorbed on the suspended YSZ particles, making them positively charged. Application of a dc field forces the positively charged YSZ particles to move towards and deposit on the substrate which is cathode.

Figure 1: SEM images showing the surface morphologies of the Ni–P layer: (a) low magnification; (b) high magnification (c) the results of the EDS analysis of Ni-P coating on AZ91D alloy.

Figure 2: SEM micrographs from cross sections of Ni-P layer on AZ91D alloy.

After drying of YSZ coating on the surface of AZ91D alloy with Ni-P interlayer in air, the coating was heat treated at 400 °C for 60 min. The morphology of YSZ coating on the surface of the magnesium alloy with Ni-P interlayer and without Ni-P interlayer after heat treatment is shown in Figure 3. It should be noted that the numerous cracks are formed in the YSZ coating because of the shrinkage of the coating and loss of water during the heat treatment (Figure 3(a) and (c)). It appears that the agglomerated particles are distributed on both surfaces. Also Figure 3 (b) and (d) show that particle size of the YSZ coating deposited on the magnesium alloy is larger than the particle size of the YSZ on the magnesium alloy with the Ni-P layer. The agglomerated particles are also observable in Figure 3(b). In addition, the statistical analysis carried out by the imager analyzer software (Clemex software) shows that the mean size of YSZ particles on magnesium alloy without Ni-P layer is larger than the mean size of YSZ particles on magnesium alloy with Ni-P layer. Figure 4 shows the cumulative diagram of the particle size of the YSZ coating on magnesium alloy with and without Ni-P layer. The results of the statistical analyses of particle sizes of YSZ coatings are tabulated in Table 4.

Also, it seems that the YSZ particles that are small readily fill the pores between the nodules of Ni-P layer and produce a composite coating including Ni-P-YSZ particles. The YSZ particles which fill the holes can close the ways of transfer of the aggressive species to magnesium alloy surface. The magnesium ions can increase the ionic intensity of the suspension that according to findings of previous studies [22] might have a negative influence on double layer and hence result in reduction of zeta potential of YSZ particles and their lower stability in the solution. Therefore, the presence of Ni-P layer can help to decrease the corrosion of the magnesium alloy. Finally it can improve the quality of the YSZ coating on the magnesium alloy.

On the other hand, the Ni-P interlayer can partially dissolve in acetyl-acetone solution and the $Ni⁺²$ ions can introduce to solution and form the hydroxide and alkoxide of Ni according to equations (6) and (7):

$$
\text{Ni}^{2+} + 2\text{OH}^- \rightarrow \text{Ni}(\text{OH})_2 \tag{6}
$$

$$
2CH_3-CH_2-O^- + Ni^{2+} \to Ni(CH_3-CH_2-O)_2 \tag{7}
$$

The presence of hydroxide can increase the adhesion of YSZ coating to the substrate because the sub-micron particles of hydroxide between the larger particles may enhance the effect of the van der Waals forces and result in an adherent deposit. Also, it is known that the flow of fine powders is hindered by the large attractive forces between the particles. Alternatively the effect of the hydroxide of Ni may be related to its polymeric structure. The flocculation of colloids can be achieved by addition of natural or synthetic polymers of high molecular weight; the polymer chain is assumed to adsorb on to the particles and the bridges are formed of them. Thus a random three-dimensional structure is built which is held together by polymer bridges [23]. Also, nickel hydroxide and nickel alkoxide that are formed can be adsorbed on the surface of YSZ particles to generate charge density and improve the zeta potential of these particles in the suspension.

m alloy is larger than the particle size of
 **Archive of the symbility of the symbility of the magnesium alloy with the Ni-P layer.

The magnesium alloy with the Ni-P layer.

The magnesium and the bridges are formed of the** The XRD pattern from YSZ coating on magnesium alloy without and with Ni-P layer after heat treatment at 400 °C for 60 min is shown in Figure 5. As it is seen from Figure 5(b), the $NiP₂$ phase is observed, which can help to increase the corrosion resistance of coating. In addition, according to Figure 5(b), The XRD pattern confirms the presence of YSZ phase with the NiO and $NiAl₂O₄$ phases. During the EPD process, the $Ni(OH)₂$ can be formed. Then, the NiO phase would be formed by decomposition of $Ni(OH)_2$ according to Equation (8). Also, it is known that the oxidation of the nickel can take place below 1000 ºC; therefore, it can also be assumed that the NiO can be formed by reaction of the Ni with oxygen in the atmosphere. This reaction is associated with volume expansion that can help to increase the density of the YSZ /Ni-P coating.

$$
\text{Ni(OH)}_2 \rightarrow \text{NiO} + \text{H}_2\text{O}
$$
 (8)

Figure 3: Surface morphology of YSZ coating on AZ91D alloy, (a) and (b) without Ni-P interlayer by low and high magnification, respectively, (c) and (d) AZ91D alloy with Ni-P interlayer by low and high magnification, respectively.

Figure 4: cumulative particle size of YSZ coatings on magnesium alloy with and without Ni-P layer.

Particle Size	Minimum (nm)	$Maximum(\mu m)$ $Mean(\mu m)$		Standard deviation (μm)	
YSZ coating with Ni-P layer	50.5	33.9	0.304	2.14	
YSZ coating without Ni-P layer	50.5	38.2	0.373	3.22	

Table 4: results of particles size of YSZ coating with Ni-P and without Ni-P layer.

Figure 5: The XRD pattern of YSZ coating on AZ91D, (a) without Ni-P layer and (b) with Ni-P layer.

3.3. EIS analysis of coating

As was mentioned earlier, potentiostatic EIS tests have been carried out at open circuit potential in 3.5% NaCl solution. The Nyquist curves of Figure 6 show the results of these tests. Figure 6(a) illustrates the Nyquist curve for the impedance test performed for AZ91D without coating and Figure 6(b) shows the Nyquist curve related to the test carried out for AZ91D with coatings.

The Nyquist diagram of AZ91D reveals a capacitive curve at high and intermediate frequencies. Many authors have related this to the metal dissolution and the oxidation-reduction reactions on the magnesium alloy surface according to equations (9) to (11) [24]. So, its diameter can be associated with charge-transfer resistance and finally associate with the corrosion resistance of the alloy. At low frequencies, a second curve or tail in Nyquist plots reveals an inductive behavior.

$$
Mg \to Mg^{2+} + 2e^-
$$
 (9)

$$
2H_2O + 2e^- \rightarrow H_2 + 2OH^-
$$
 (10)

$$
Mg + 2H_2O \to Mg(OH)_2 + H_2
$$
 (11)

The Nyquist diagram of YNi-AZ sample shows two capacitive curves. The capacitive one at high and medium frequencies can be related to the presence of coatings on the magnesium alloy surface and the low frequencies capacitive arc can be associated with corrosion process on magnesium alloy surface. In addition, an inductive behavior is observed in the Nyquist plot of the magnesium alloy without coating. Numerous examples of such inductive arcs are found in corrosion studies, and various explanations for them have been suggested, mainly involving a potentialdependent adsorption of this part of the impedance plot seems to be rather complicated and is immaterial in studies of electrochemical corrosion, in which the kinetic information is estimated from the capacitive arcs.

Figure 6: The Nyquist curve of (a) uncoated sample and (b) coated sample.

The equivalent circuits used to explain the corrosion behavior of AZ and YNi-AZ samples are shown in Figure 7. The suitable equivalent circuit for analyzing the corrosion behavior of AZ sample is presented in Figure 7 (a). The circuit model for the YNi-AZ is presented in Figure 7(b).

In these circuit models, R_s represents the solution resistance, C_{cont} is the capacitance of the constant phase element (an indicator of the capacity of the coat), and n_1 is the power associated with it. In addition, R_{coat} is the coating resistance, C_{dl} is the double layer constant phase element (an indicator of the double layer capacitance between AZ91D alloy surface and the solution), and n_{dl} is the constant phase element power associated with it, R_t is charge-transfer resistance of the corrosion reaction, L_{adsorp} is the inductance, and R_{adsorp} represents the inductance real resistance. The impedance parameters based on the proposed circuit model were calculated by use of Zview software, in other words using the software's numerical methods, appropriate values are fitted on the measured data and these values are shown in Tables 5 with the sum of weighted squares.

Also, the equation (12) shows the formula for calculating the capacitance of the constant phase element impedance. In this equation, Z_{CPE} is the impedance of the constant phase element, C represents

the capacitance, ω stands for the frequency, n is the constant phase element exponent, and it is the imaginary part. It is also worth noting that n varies between 0 and 1 [25].

$$
Z_{\rm CPE} = \left[C(\omega i)^n \right]^{-1} \tag{12}
$$

According to equation (11), by decreasing the capacitance, the capacitive impedance increases. Therefore, in the corrosion process, if the chargetransfer capacitance decreases, it will be expected that the charge- transfer resistance increases. The YSZ and the Ni-P coatings can act as barrier layers which exclude corrosive species from the surface of the magnesium alloy and end to decrease the chargetransfer capacitance of the double layer that is formed between the magnesium alloy and the corrosive solution. So by applying these coatings to AZ91D substrate, the charge transfer resistance of the alloy increases. The results from Table 5 show the effective improvement of the charge transfer resistance of AZ91D with coatings in the chloride solution. On the other hand, the Ni-P layer can act as a cathodic surface on the magnesium alloy surface and can reduce the surface activity of the magnesium alloy.

Figure 7: Circuit models proposed for the electrochemical impedance data measured (a) related to uncoated sample and (b) coated sample.

Sample	R_{S} $(\Omega$.cm ²)	C_{dl} $(\mu F/cm^{-2})$	n_{dl}	\mathbf{R}_t $(\Omega$.cm ²)	C_{coat} $(\mu \text{F/cm}^{-2})$	n_{coat}	R_{coat} $(k\Omega.cm^2)$	L_{adsorp} (kH/cm ²)	R_{adsorp} $(k\Omega.cm^2)$	Sum of weighted squares
AZ	1.87	3.9	0.76	1470.2	$---$	$---$	$---$	4.52	4.9	0.06
YNi-AZ	1.81	4.6	0.81	7032.1	1.01	0.9	322.6	---	$---$	0.07

Table 5: Circuit element values calculated by fitting the model presented in Figure 7.

Figure 8: SEM micrograph of coated surface after indentation test, (a) low magnification, (b) and (c) high magnification.

3.4. Indentation analysis coating

*Archive of coated surface after indentation test, (a) low magnification, (b) and (c) high magninal
 Archive of the Rockwell indentations are altersion of YSZ cedaring to the substrate. Also

are seen that the load of 15* The SEM images of the Rockwell indentations are shown in Figure 8. It can be seen that the load of 150 N led to radial plastic deformation of the coating which caused circumferential cracking of the film outside the indentation area. Through-thickness cracks were observed on coating which may be related to the elastic-plastic boundary of the substrates. The indentation marks had a diameter of ~1.6 mm on the coated sample which would cause more deformation at the edge. According to Figure 8, the interfacial bond is adequate, so that, there is some indication of delamination at fracture area of substrate. Also, the radial micro-cracks (identified by white circles in Figure 8) are seen and the fracture of YSZ-Ni-P coating is more brittle, however the ductile areas are seen beside brittle areas as marked by arrows in Figure 8(c). The presence of Ni-P on AZ91D alloy can help to increase the roughness of surface which leads to the increase of effective mechanical interlocking between the YSZ coating and rough substrate. During the EPD process, the presence of Ni-P interlayer results in the

formation of hydroxide which can increase the adhesion of YSZ coating to the substrate. Also, the Ni-P layer can bond well to substrate because of the existence of a stronger metal-to-metal bonding during the EN deposition.

4. Conclusion

Deposition of Ni-P layer on AZ91D alloy can hinder the dissolution of AZ91D alloy in acetyl acetoneethanol solutions and it can help to stabilize suspension of YSZ particles, so that, the agglomeration of YSZ particles on AZ91D alloy with Ni-P layer is less than the agglomeration of YSZ particles on AZ91D alloy without Ni-P layer. Furthermore, after heat treatment at 400° C, the NiP₂ can be produced that can help to increase the corrosion resistance of AZ91D alloy with the YSZ coating in corrosive media. In addition, the Ni-P / YSZ coating improve the corrosion resistance of AZ91D in NaCl solution by increasing the chargetransfer resistance of the surface. The interfacial bond between coating and substrate is adequate that it can be related to the presence of Ni-P interlayer.

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پوشش دهی الکتروفور تیک 3YSZ بر آلیاژ AZ91 همراه با لایه میانی Ni-P

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واژه هاي كليدي:

زير كونيا پوشش‹هي الكتروفورتيک AZ91 لایه میانی Ni-P

اكثرى كروه م_ايندسى موات دائشگذه مهندسى مكانيگ، دائشگاه تبريز، تبريز، ايران مندوق پستي: ۱۳۹۱-۱۳۶۶هها
روه مهندسى مواد، دائشگذه مهندسى مكانيگ، دائشگاه تبريز، بريز، ايران، مندوق پستى: ۱۳۶۴-۱۳۶۴هها
شهر ما توان دائشگذه مهندسى زير كونياي پايدار شده با ٣ درصد مولي اكسيد ايتريم (3YSZ) با روش الكتروفورتيک از محلول غير آبی بر سطح آلیاژ AZ91 اعمال شد. همچنين، لايه ميانی Ni-P بين زيرلايه و پوشش 3YSZ با روش الكترولس اعمال شد. در نهایت، زیرلایه همراه با پوششها در دمای ۴۰۰ درجه سانتی گراد در شرايط اتمسفر كنترل شده، عمليات حرارتي شد. آماده سازي پوششها، ميكروساختار و مقاومت به خوردگی آنها بررسی شد. از میكروسكوپ الكترونی روبشی (SEM) به منظور بررسی ریخت شناسی پوشش&ا استفاده شد. به علاوه، آنالیز فازی سطح با استفاده از پراش اشعه ایکس (XRD) انجام شد. به منظور بررسی مقاومت به خوردگی، روش آنالیز امپدانس الکتروشیمیایی (EIS) در محلول ٣/۵ درصد وزنى كلريد سديم بكار رفت. همچنين به منظور بررسى پايدارى پوشش از آزمون فرورونده راكول سي مطابق استاندار (VDI 3198 norm) استفاده شد. نتايج نشان داد كه لايه هیانی Ni-P می تواند کیفیت پوشش زیرکونیایی را بهبود دهد. همچنین پوشش YSZ-Ni-P، مقاومت به انتقال بار را در سطح آلياژ AZ91 در محلول كلريدى افزايش مى دهد.

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